



Material Content Data Sheet



Sales Product Name	TLE4291E			Issued	27. September 2017			
MA#	MA001020468							
Package	PG-SSOP-14-2			Weight*	83.04 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.154	2.59	2.59	25940	25940
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8298	
wire	non noble metal	copper	7440-50-8	27.978	33.69	34.57	336920	345737
	noble metal	gold	7440-57-5	0.153	0.18	0.18	1840	1840
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1194
encapsulation	plastics	epoxy resin	-	4.559	5.49		54904	
	inorganic material	silicondioxide	60676-86-0	44.898	54.08	59.69	540685	596783
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11755	11755
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9244	9244
glue	plastics	epoxy resin	-	0.181	0.22		2175	
	noble metal	silver	7440-22-4	0.542	0.65	0.87	6526	8701
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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